

11-26-04

IFW

Andrews & Kurth L.L.P.
111 Congress Avenue, Suite 1700
Austin, Texas 78701
512.320.9200 Phone
512.320.9292 Fax
andrewskurth.com

J. Scott Denko
512.320.9259 Direct
scottdenko@akllp.com

Via Express Mail
No. EV434215837US

November 23, 2004

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Re: Application No.: 09/633,297
Filing Date: August 3, 2000
Title: Reissue: Modular Panel Stacking Process
Inventors: Aaron U. Levy, et al.
Docket No. DPAC-015X

Dear Commissioner:

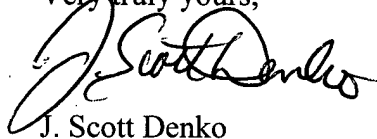
Please find enclosed the following items:

- 1) Copy of Power of Attorney To Prosecute Applications Before the USPTO;
- 2) Statement Under 37 CFR 3.73(b); and
- 3) a return postcard for confirmation of receipt.

The Commissioner is hereby authorized to charge any fees deemed to be due or credit any overpayment to Deposit Account No. 50-0897, upon which the undersigned is authorized to sign.

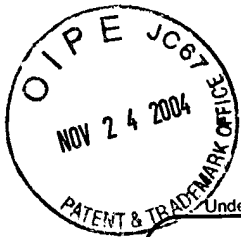
Please return the postcard confirming your receipt of the enclosed materials.

Very truly yours,



J. Scott Denko

Enclosures



PTO/SB/82 (09-04)

Approved for use through 11/30/2005. OMB 0651-0035

U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

**REVOCATION OF POWER OF
ATTORNEY WITH
NEW POWER OF ATTORNEY
AND
CHANGE OF CORRESPONDENCE ADDRESS**

Application Number	091633,297
Filing Date	8/3/00
First Named Inventor	Aaron U. Levy
Art Unit	
Examiner Name	
Attorney Docket Number	DPAC - OISX

I hereby revoke all previous powers of attorney given in the above-identified application.

☐ A Power of Attorney is submitted herewith.

OR

☒ I hereby appoint the practitioners associated with the Customer Number:

36,485

☒ Please change the correspondence address for the above-identified application to:

☒ The address associated with
Customer Number:

36,485

OR

☐ Firm or
Individual Name

Address

City

State

Zip

Country

Telephone

Fax

I am the:

☐ Applicant/Inventor.

☒ Assignee of record of the entire interest. See 37 CFR 3.71.
Statement under 37 CFR 3.73(b) is enclosed. (Form PTO/SB/96)

SIGNATURE of Applicant or Assignee of Record

Signature *Stephanie Lucie*

Name Stephanie Lucie

Date 11/18/04

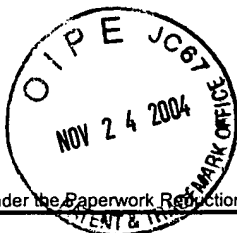
Telephone 512-454-9531

NOTE: Signatures of all the inventors or assignees of record of the entire interest or their representative(s) are required. Submit multiple forms if more than one signature is required, see below*.

☐ *Total of _____ forms are submitted.

This collection of information is required by 37 CFR 1.36. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11 and 1.14. This collection is estimated to take 3 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

If you need assistance in completing the form, call 1-800-PTO-9199 and select option 2.



Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

STATEMENT UNDER 37 CFR 3.73(b)Applicant/Patent Owner: Staktek Group L.P. (Inventor: Aaron U. Levy, et al.)Application No./Patent No.: 09/633,297 Filed/Issue Date: 8/3/2000Entitled: Reissue: Modular Panel Stacking ProcessStaktek Group L.P., a limited partnership
(Name of Assignee) (Type of Assignee, e.g., corporation, partnership, university, government agency, etc.)

states that it is:

1. ☒ the assignee of the entire right, title, and interest; or
2. ☐ an assignee of less than the entire right, title and interest.
The extent (by percentage) of its ownership interest is _____ %

in the patent application/patent identified above by virtue of either:

- A. ☐ An assignment from the inventor(s) of the patent application/patent identified above. The assignment was recorded in the United States Patent and Trademark Office at Reel _____, Frame _____, or for which a copy thereof is attached.

OR

- B. ☒ A chain of title from the inventor(s), of the patent application/patent identified above, to the current assignee as shown below:

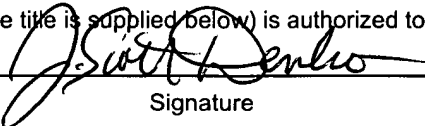
1. From: Aaron U. Levy, et al. To: Dense-Pac Microsystems, Inc.
The document was recorded in the United States Patent and Trademark Office at
Reel 8832, Frame 0596, or for which a copy thereof is attached.
2. From: Dense-Pac Microsystems, Inc. To: DPAC Technologies Corp.
The document was recorded in the United States Patent and Trademark Office at
Reel 014697, Frame 0518, or for which a copy thereof is attached.
3. From: _____ To: _____
The document was recorded in the United States Patent and Trademark Office at
Reel _____, Frame _____, or for which a copy thereof is attached.

☐ Additional documents in the chain of title are listed on a supplemental sheet.

- ☒ Copies of assignments or other documents in the chain of title are attached.

[NOTE: A separate copy (i.e., a true copy of the original assignment document(s)) must be submitted to Assignment Division in accordance with 37 CFR Part 3, if the assignment is to be recorded in the records of the USPTO. See MPEP 302.08]

The undersigned (whose title is supplied below) is authorized to act on behalf of the assignee.



Signature

November 24, 2004

Date

J. Scott Denko

Printed or Typed Name

512-320-9200

Telephone Number

Attorney of Record, Reg. No. 37,606

Title

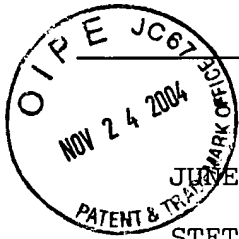
This collection of information is required by 37 CFR 3.73(b). The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11 and 1.14. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

If you need assistance in completing the form, call 1-800-PTO-9199 and select option 2.



UNITED STATES PATENT AND TRADEMARK OFFICE

UNDER SECRETARY OF COMMERCE FOR INTELLECTUAL PROPERTY AND
DIRECTOR OF THE UNITED STATES PATENT AND TRADEMARK OFFICE



JUNE 07, 2004

PTAS



102604190A

STETINA BRUNDA ET AL.
KIT M. STETINA, ESQ.
75 ENTERPRISE, SUITE 250
ALISO VIEJO, CA 92656

UNITED STATES PATENT AND TRADEMARK OFFICE
NOTICE OF RECORDATION OF ASSIGNMENT DOCUMENT

THE ENCLOSED DOCUMENT HAS BEEN RECORDED BY THE ASSIGNMENT DIVISION OF THE U.S. PATENT AND TRADEMARK OFFICE. A COMPLETE MICROFILM COPY IS AVAILABLE AT THE ASSIGNMENT SEARCH ROOM ON THE REEL AND FRAME NUMBER REFERENCED BELOW.

PLEASE REVIEW ALL INFORMATION CONTAINED ON THIS NOTICE. THE INFORMATION CONTAINED ON THIS RECORDATION NOTICE REFLECTS THE DATA PRESENT IN THE PATENT AND TRADEMARK ASSIGNMENT SYSTEM. IF YOU SHOULD FIND ANY ERRORS OR HAVE QUESTIONS CONCERNING THIS NOTICE, YOU MAY CONTACT THE EMPLOYEE WHOSE NAME APPEARS ON THIS NOTICE AT 703-308-9723. PLEASE SEND REQUEST FOR CORRECTION TO: U.S. PATENT AND TRADEMARK OFFICE, ASSIGNMENT DIVISION, BOX ASSIGNMENTS, CG-4, 1213 JEFFERSON DAVIS HWY, SUITE 320, WASHINGTON, D.C. 20231.

RECORDATION DATE: 11/17/2003

REEL/FRAME: 014697/0518

NUMBER OF PAGES: 6

BRIEF: CHANGE OF NAME (SEE DOCUMENT FOR DETAILS).

ASSIGNOR:

DENSE-PAC MICROSYSTEMS, INC.

DOC DATE: 11/07/1997

ASSIGNEE:

DPAC TECHNOLOGIES CORP.
7321 LINCOLN WAY
GARDEN GROVE, CALIFORNIA 92641

SERIAL NUMBER: 09633297

FILING DATE: 08/03/2000

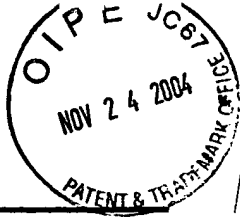
PATENT NUMBER:

ISSUE DATE:

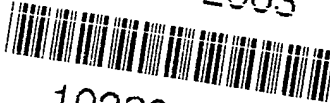
TITLE: MODULAR PANEL STACKING PROCESS

014697/0518 PAGE 2

JEFFREY OLSEN, EXAMINER
ASSIGNMENT DIVISION
OFFICE OF PUBLIC RECORDS



11-19-2003



102604190

Form PTO-1595
(Rev. 10/02)

OMB No. 0651-0027 (exp. 6/30/2005)

Tab settings ⇌ ⇌ ⇌

RE

U.S. DEPARTMENT OF COMMERCE
U.S. Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
Dense-Pac Microsystems, Inc.

11-17-03

2. Name and address of receiving party(ies)

Name: DPAC Technologies Corp.

Internal Address: _____

7321 Lincoln Way

Garden Grove, California 92641

Street Address: _____

same as above

City: _____ State: _____ Zip: _____

Additional name(s) & address(es) attached? ☐ Yes ☒ NoAdditional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☐

Assignment

☐

Merger

☐

Security Agreement

☒

Change of Name

☐

Other _____

Execution Date: 11/07/1997

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s) 09/633,297

B. Patent No.(s) _____

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Kit M. Stetina, Esq.

Internal Address: STETINA BRUNDA ET AL.

75 Enterprise, Suite 250

Aliso Viejo, California 92656

Street Address: same as above

City: _____ State: _____ Zip: _____

6. Total number of applications and patents involved: ☐

7. Total fee (37 CFR 3.41).....\$ _____

☐

Enclosed

PREVIOUSLY SUBMITTED

☐

Authorized to be charged to deposit account

8. Deposit account number:

19-4330

2003 NOV 17 AM 8:42
OPR/FINANCE

DO NOT USE THIS SPACE

9. Signature.

Kit M. Stetina

Name of Person Signing

Signature

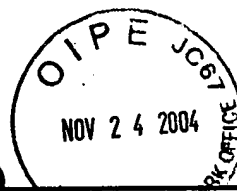
11/10/2003

Date

Total number of pages including cover sheet, attachments, and documents: ☐

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231



Form PTO-1595
(Rev. 03/01)
OMB No. 0651-0027 (exp. 5/31/2002)
Tab settings ⇌ ⇌ ⇌ ▼

OFFICE OF PUBLIC RECORDS
DEPARTMENT OF COMMERCE
U.S. Patent and Trademark Office
2003 MAY -5 PM 10:44

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

AARON URI LEVY

See 1 in Addendum

5.5.03

2. Name and address of receiving party(ies)

Name: DPAC TECHNOLOGIES CORP.

Internal Address: _____

Street Address: 7321 LINCOLN WAY

City: GARDEN GROVE State: CA Zip: 92641

Additional name(s) of conveying party(ies) attached? ☒ Yes ☐ No

3. Nature of conveyance:

☐ Assignment

☐ Merger

☐ Security Agreement

☒ Change of Name

☐ Other _____

Execution Date: NOVEMBER 7, 1997

Additional name(s) & address(es) attached? ☐ Yes ☐ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s)

09/633,297

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: KIT M. STETINA

Internal Address: _____

Street Address: 75 Enterprise-Suite 250

City: Aliso Viejo State: CA Zip: 92656

6. Total number of applications and patents involved: ☐ 1

7. Total fee (37 CFR 3.41).....\$ 40

☒ Enclosed

☐ Authorized to be charged to deposit account

8. Deposit account number: _____

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

KIT M. STETINA

Name of Person Signing

Signature

Date

4/30/03

Total number of pages including cover sheet, attachments, and documents ☐ 5

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

05/05/2003 UNELLER 00000060-09633297

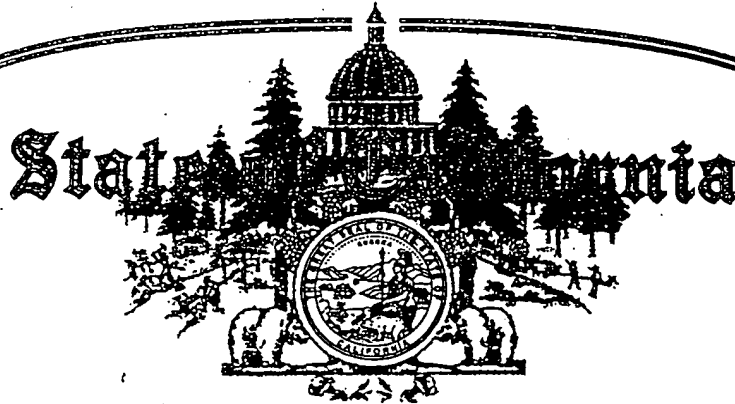
01 FC:0021

40.00-00

Attachment to Form PTO - 1595
Recordation Form Cover Sheet

Additional Conveying Parties

- JOHN PATRICK SPRINT
- JOHN ARTHUR FORTHUN
- HARLAN RUBEN ISAAK
- JOEL ANDREW MEARIG
- MARK CHANDLER CALKINS



SECRETARY OF STATE

I, *BILL JONES*, Secretary of State of the State of California, hereby certify:

That the attached transcript of 2 page(s) has been compared with the record on file in this office, of which it purports to be a copy, and that it is full, true and correct.

IN WITNESS WHEREOF, I execute this certificate and affix the Great Seal of the State of California this day of

AUG 17 2001

Bill Jones
Secretary of State

A0569044

**CERTIFICATE OF AMENDMENT
OF ARTICLES OF INCORPORATION OF
DENSE-PAC MICROSYSTEMS, INC.**

ENDORSED - FILED
in the office of the Secretary of State
of the State of California

AUG 15 2001

Edward G. Bruce and William Stowell hereby certify that:

BILL JONES, Secretary of State

1. They are the President and Secretary, respectively, of Dense-Pac Microsystems, Inc., a California corporation (the "Corporation").

2. Article I of the Articles of Incorporation of this Corporation is amended to read in its entirety as follows:

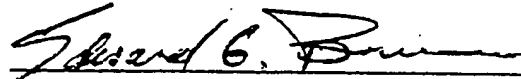
I

The name of this corporation is DPAC Technologies Corp.

3. The foregoing amendment to the Corporation's Articles of Incorporation has been duly approved by the Board of Directors.

4. The foregoing amendment to the Corporation's Articles of Incorporation has been duly approved by the required vote of shareholders of the Corporation in accordance with Section 902 of the California Corporations Code. The total number of outstanding shares at the record date for the shareholder was 20,950,589 shares of Common Stock. The number of shares of each series or class voting in favor of the foregoing amendment equaled or exceeded the vote required. The percentage vote required was more than 50% of the outstanding shares of Common Stock.

Each of the undersigned declares under penalty of perjury that the matters set out in the foregoing Certificate are true of his own knowledge. Executed this 10th day of August, 2001, in Garden Grove, California.

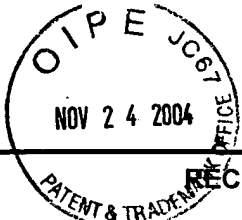


Edward G. Bruce, President



William Stowell, Secretary





Form PTO-1595
(Rev. 03/01)

OMB No. 0651-0027 (exp. 5/31/2002)

Tab settings ⇌ ⇌ ⇌ ▼ ▼ ▼ ▼ ▼ ▼ ▼

RECORDATION FORM COVER SHEET PATENTS ONLY

U.S. DEPARTMENT OF COMMERCE
U.S. Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

AARON URI LEVY
See 1 in Addendum

Additional name(s) of conveying party(ies) attached? ☒ Yes ☐ No

3. Nature of conveyance:

- ☐ Assignment ☐ Merger
☐ Security Agreement ☒ Change of Name
☐ Other _____

Execution Date: NOVEMBER 7, 1997

2. Name and address of receiving party(ies)

Name: DPAC TECHNOLOGIES CORP.

Internal Address: _____

Street Address: 7321 LINCOLN WAY

City: GARDEN GROVE State: CA Zip: 92641

Additional name(s) & address(es) attached? ☐ Yes ☐ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s)
09/633,297

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: KIT M. STETINA

Internal Address: _____

Street Address: 75 Enterprise-Suite 250

City: Aliso Viejo State: CA Zip: 92656

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$ 40

☒ Enclosed

☐ Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

KIT M. STETINA
Name of Person Signing


Signature

4/30/03
Date

Total number of pages including cover sheet, attachments, and documents 5

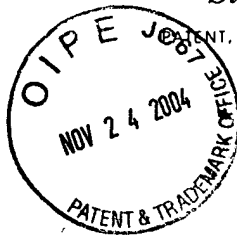
LAW OFFICES

Stetina Brunda Garred & Brucker

A PROFESSIONAL CORPORATION

PATENT, TRADEMARK, COPYRIGHT AND UNFAIR COMPETITION CAUSES

75 ENTERPRISE, SUITE 250
ALISO VIEJO, CALIFORNIA 92656



KIT M. STETINA
BRUCE B. BRUNDA
WILLIAM J. BRUCKER
MARK B. GARRED
MATTHEW A. NEWBOLES
ERIC L. TANEZAKI
LOWELL ANDERSON

MARLENE KLEIN
IN H. KIM
SEAN O'NEILL
BRENT A. FOLSOM
MICHAEL D. NORNBERG *

JESSIE WANG †
JAMES C. YANG †

TELEPHONE (949) 855-1246
FACSIMILE I (949) 855-6371
FACSIMILE II (949) 716-8197

www.stetinalaw.com

Writer's Direct E-mail:
kstetina@stetinalaw.com

November 7, 2003

United States Patent and Trademark Office
Assignment Division
Box Assignments, CG-4
1213 Jefferson Davis Highway, Suite 320
Washington, D.C. 20231

RE: United States Patent No.: 09/633,297
For **MODULAR PANEL STACKING PROCESS**
- Aaron U. Levy -
Our Ref: **DENSE-015X**
Document ID No.: 102439917

Dear Sir or Madam:


Enclosed herewith are the following documents:

1. Notice of Non-Recordation of Document;
2. New Patents Only Cover Sheet; and
3. Return postcard.

If you should have any questions or require additional information, please contact the attorney listed below. If additional fees are required in relation to this matter, please charge deposit account no. 19-4330.

Respectfully submitted,

STETINA BRUNDA GARRED & BRUCKER



Kit M. Stetina



UNITED STATES
PATENT AND
TRADEMARK OFFICE

OCTOBER 08, 2003

PTAS

Under Secretary of Commerce For Intellectual Property and
Director of the United States Patent and Trademark Office
Washington, DC 20231
www.uspto.gov

KIT M. STETINA
75 ENTERPRISE-SUITE 250
ALISO VIEJO, CA 92656



102439917A

UNITED STATES PATENT AND TRADEMARK OFFICE
NOTICE OF NON-RECORDATION OF DOCUMENT

DOCUMENT ID NO.: 102439917

THE ENCLOSED DOCUMENT HAS BEEN EXAMINED AND FOUND NON-RECORDABLE BY THE ASSIGNMENT DIVISION OF THE U.S. PATENT AND TRADEMARK OFFICE. THE REASON(S) FOR NON-RECORDATION ARE STATED BELOW. DOCUMENTS BEING RESUBMITTED FOR RECORDATION MUST BE ACCOMPANIED BY A NEW COVER SHEET REFLECTING THE CORRECT INFORMATION TO BE RECORDED AND THE DOCUMENT ID NUMBER REFERENCED ABOVE.

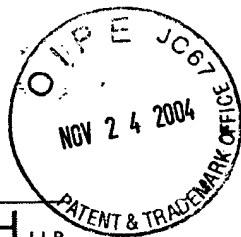
THE ORIGINAL DATE OF FILING OF THIS ASSIGNMENT DOCUMENT WILL BE MAINTAINED IF RESUBMITTED WITH THE APPROPRIATE CORRECTION(S) WITHIN 30 DAYS FROM THE DATE OF THIS NOTICE AS OUTLINED UNDER 37 CFR 3.51. THE RESUBMITTED DOCUMENT MUST INCLUDE A STAMP WITH THE OFFICIAL DATE OF RECEIPT UNDER 37 CFR 3. APPLICANTS MAY USE THE CERTIFIED PROCEDURES UNDER 37 CFR 1.8 OR 1.10 FOR RESUBMISSION OF THE RETURNED PAPERS, IF THEY DESIRE TO HAVE THE BENEFIT OF THE DATE OF DEPOSIT IN THE UNITED STATES POSTAL SERVICE.

SEND DOCUMENTS TO: U.S. PATENT AND TRADEMARK OFFICE, ASSIGNMENT DIVISION, BOX ASSIGNMENTS, CG-4, 1213 JEFFERSON DAVIS HWY, SUITE 320, WASHINGTON, D.C. 20231. IF YOU HAVE ANY QUESTIONS REGARDING THIS NOTICE, YOU MAY CONTACT THE INDIVIDUAL WHOSE NAME APPEARS ON THIS NOTICE AT 703-308-9723.

1. THE COVER SHEET SUBMITTED FOR RECORDING IS NOT ACCEPTABLE FOR A CHANGE OF NAME. THE FORMER NAME OF DPAC TECHNOLOGIES CORP. SHOULD BE THE ONLY CONVEYING PARTY.

JEFFREY OLSEN, EXAMINER
ASSIGNMENT DIVISION
OFFICE OF PUBLIC RECORDS

ANDREWS
ATTORNEYS KURTH LLP



Andrews & Kurth L.L.P.
111 Congress Avenue, Suite 1700
Austin, Texas 78701
512.320.9200 Phone
512.320.9292 Fax
andrewskurth.com

J. Scott Denko
512.320.9259 Direct
scottdenko@akllp.com@andrewskurth.com

Via Express Mail
No. EV434216276US

June 28, 2004

Box Fee – Assignment Division
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Re: Application No.: 09/633,297
 Filing Date: 08/03/2000
 Title: Reissue: Modular Panel Stacking Process
 Inventors: A. Levy, et al
 Docket No. DPAC-015X

Dear Commissioner:

Please find enclosed the following items:

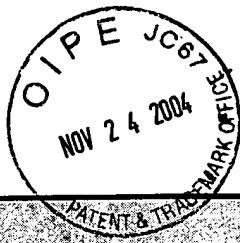
- 1) Assignment, together with Assignment Recordation Form (with duplicate copy);
- 2) Fee Form 2004 (with duplicate copy); and
- 3) a return postcard for confirmation of receipt.

The Commissioner is hereby authorized to charge any fees deemed to be due or credit any overpayment to Deposit Account No. 50-0897, upon which the undersigned is authorized to sign.

Please return the postcard confirming your receipt of the enclosed materials.

Very truly yours,

J. Scott Denko



Attorney Docket No.: DPAC-015X

Form PTO-1619A
Expires 06/30/99
OMB 0651-0027U.S. Department of Commerce
Patent and Trademark Office**RECORDATION FORM COVER SHEET
PATENTS ONLY**TO: THE HONORABLE COMMISSIONER OF PATENTS AND TRADEMARKS: *Please record the attached original document(s) or copy(ies).***SUBMISSION TYPE**

- ☒ New
☐ Resubmission (non-recordations)
Document ID # _____
☐ Correction of PTO Error
Reel # _____ Frame # _____
☐ Corrective Document
Reel # _____ Frame # _____

CONVEYANCE TYPE

- ☒ Assignment
☐ Change of Name
☐ Security Agreement
☐ Merger
Other: _____

CONVEYING PARTY(IES)

Name (line 1): DPAC Technologies Corp.
Name (line 2): (formerly known as Dense-Pac
Name (line 3): Microsystems, Inc.)
Name (line 4): _____
Name (line 5): _____
Name (line 6): _____
Name (line 7): _____
Execution Date: June 9, 2004
☐ Mark if additional names of conveying parties attached.

RECEIVING PARTY(IES):

Name: Staktek Group L.P.
Address: 8900 Shoal Creek Blvd., Suite 125
City: Austin
State: TX Zip: 78757

☐ If document to be recorded is an assignment and the receiving party is not domiciled in the United States, an appointment of a domestic representative is attached. (*Designation must be a separate document from Assignment.*)

PAGES Enter the total number of pages of the attached conveyance document, including any attachments. 10**APPLICATION NUMBER(S) OR PATENT NUMBER(S)** ☐ Mark if additional numbers attached.*Enter either the Patent application number or the patent number (DO NOT ENTER BOTH numbers for the same property)*

Patent Application No(s):

09/633,297

_____Patent No(s):

If this document is being filed together with a new patent application, enter the date the application was signed by the first named executing inventor:

CORRESPONDENT NAME AND ADDRESS

Name: J. Scott Denko
Internal address: Andrews & Kurth LLP
111 Congress Avenue, Suite 1700

Street address: Same

City: Austin
State: Texas Zip: 78701

PATENT COOPERATION TREATY (PCT)

Enter PCT application number
only if a U.S. application number
has not been assigned.

PCT _____
PCT _____
PCT _____

PCT _____
PCT _____
PCT _____

PCT _____
PCT _____
PCT _____

NUMBER OF PROPERTIES

Enter the total number of properties involved: One (1)

FEE AMOUNT

For Amount for Properties Listed (37 CFR 3.41):

\$40.00

Method of Payment:



Enclosed (included in the check covering the filing fee), or



Deposit Account

(Enter for payment by deposit account or if additional fees can be charged to the account.)



Debit Account No.: 50-0897

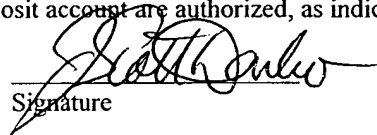


Authorized to charge additional fees or credit any overpayment to Deposit Account
No. 50-0897.

STATEMENT AND SIGNATURE

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Charges to deposit account are authorized, as indicated herein.

J. Scott Denko
Name of Person Signing


Signature

June 28, 2004
Date

06/08/04

**EXHIBIT A
ASSIGNMENT OF DPAC ASSETS**

WHEREAS, DPAC Technologies Corp. (formerly known as Dense-Pac Microsystems, Inc.) ("DPAC") owns certain intellectual properties consisting of inventions, patents, and patent applications (enumerated on attached and incorporated Exhibit 1) (the "DPAC Assets");

WHEREAS, Staktek Group L.P., a Texas limited partnership, desires to acquire and DPAC desires to assign to Staktek Group L.P., all of DPAC's rights in the DPAC Assets;

NOW, THEREFORE, DPAC, for itself and its predecessors in interest for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, does hereby ASSIGN to Staktek Group L.P., all right, title and interest in the DPAC Assets, this assignment including, but not being limited to:

1. The ASSIGNED INVENTIONS enumerated on Exhibit 1 whether created by DPAC, its predecessors, its legal representatives or its assigns in the United States or any other country or place anywhere in the world;
2. The ASSIGNED PATENTS enumerated on Exhibit 1;
3. The ASSIGNED PATENT APPLICATIONS enumerated on Exhibit 1;
4. All rights of action on account of past, present, and future unauthorized use or infringement of said DPAC Assets including, but not limited to all rights to damages so accrued;
5. The right, where allowed by law, to file in the name of Staktek Group L.P. applications for patent and like protection for any one or more of the DPAC Assets in any country or countries foreign to the United States;
6. All international and domestic rights or priorities associated with any one of the DPAC Assets; and

This Assignment shall be binding upon and shall inure to the benefit of the successors, assigns, and legal representatives of the parties.

06/08/04

EXECUTED on the EFFECTIVE DATE indicated below:

Assignor: DPAC TECHNOLOGIES CORP.

Date: JUNE 9, 2004

By: [Signature]
[DPAC TECHNOLOGIES CORP OFFICER]

Name: CREIGHTON K. EARLY

Title: CHIEF EXECUTIVE OFFICER

THE STATE OF Calif]

COUNTY OF Orange]

§
§
§

This instrument was acknowledged by DPAC Officer on this the 9 day of June, 2004.

(Seal)

[Signature]
Notary Public in and for the State of []

My commission expires: 9/25/04

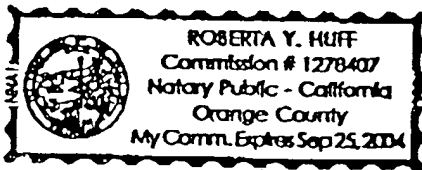


EXHIBIT 1 - DPAC Assets

Updated: January 28, 2004

Case	Title/Mark - Invention	Item Type	Patent Type	Filing Date	Serial Number	Issue Date	Patent Trademark Registration Number	Description	Status	Action Required	Date Required Action
DENSE-002A	Universal Package and Method of Forming the Same	Patent	Original	4/23/1999	09/298,664	4/24/2001	6,222,737	Universal Package and Method of Forming the Same	Issued, 3 1/2 year maintenance fees due 10/24/04.	N/A	None
DENSE-002G	Universal Package and Method of Forming the Same	Patent	Divisional	9/19/2000	09/664,938	3/26/2002	6,360,433	Universal Package and Method of Forming the Same	Issued, 3 1/2 year maintenance fees due 09/26/05.	N/A	None
DENSE-003A	Stackable Chip Package with Flex Carrier	Patent	Original	1/13/2000	09/482,294	7/21/2001	6,262,895	Stackable Chip Package with Flex Carrier	Issued, 3 1/2 year maintenance fees due 01/17/05.	N/A	None
DENSE-003C	Stackable Chip Package with Flex Carrier	Patent	Continuation	4/10/2001	09/838,773	10/29/2002	6,473,308	Stackable Chip Package with Flex Carrier	Issued, 3 1/2 year maintenance fees due 04/29/2006.	N/A	None
DENSE-005A	CSP Stacking Technology Using Rigid/Flex Construction	Patent	Original	3/24/2000	09/535,641	8/20/2002	6,437,433 B1	CSP Stacking Technology Using Rigid/Flex Construction	Issued, 3 1/2 year maintenance fees due 02/20/2006.	PTO	None
DENSE-012A	Mechanically Registered and Interconnected Chip Stack	Patent	Original	6/15/2000	09/594,989			Mechanically Registered and Interconnected Chip Stack	Closed.	N/A	None
DENSE-012G	Mechanically Registered and Interconnected Chip Stack	Patent	Divisional	7/24/2002	10/202,185			Mechanically Registered and Interconnected Chip Stack	Issued, 3 1/2 year maintenance fees due 12/09/2006.	PTO	None
DENSE-013A	Chip Stack and Method of Making Same	Patent	Original	4/13/1995	08/421,801	3/18/1997	5,612,570	Chip Stack and Method of Making Same	Issued, 7 1/2 year maintenance fees due 09/18/2004.	N/A	None
ISE-013PC	Chip Stack and Method of Making Same	Patent	PCT					Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-015A	Modular Panel Stacking Process	Patent	Original	11/17/1997	08/971,499	02/09/1999	5,869,353	Modular Panel Stacking Process	Issued, 7 1/2 year maintenance fees due 08/09/2007.	N/A	None
DENSE-015X	Retainer: Modular Panel Stacking Process	Patent	Re-issue	8/3/2000	09/653,297			Modular Panel Stacking Process	Awaiting Reply re: Non-Recordation of Document	PTO	None
DENSE-016A	IC Chip Package Having Chip Attached to and Wire Bonded within an Overlying Substrate	Patent	Original		07/851,755			IC Chip Package Having Chip Attached to and Wire Bonded within an Overlying Substrate	Closed.	N/A	None

EXHIBIT 1 - DPAC Assets

Updated: January 28, 2004

06/08/04

Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required & Owner	Date Required Action Assigned
DENSE-016EP	IC Chip Package and Method of Making the Same	Patent	European		93908306.9			IC Chip Package and Method of Making the Same	Closed.	N/A	None
DENSE-016P	IC Chip Package and Method of Making the Same	Patent	Japan		5-516611			IC Chip Package and Method of Making the Same	Closed.	N/A	None
DENSE-016PC	IC Chip Package and Method of Making the Same	Patent	PCT	3/10/1993	PCT/US93/02202			IC Chip Package and Method of Making the Same	Closed.	N/A	None
DENSE-016G	IC Chip Package Having Chip Attached to and Wire Bonded within an Overlying Substrate	Patent	Divisional	7/29/1992	07/920,763	5/17/1994	5,313,096	IC Chip Package having Chip Attached to and Wire Bonded within an Overlying Substrate	Issued. 11 1/2 year maintenance fee due 11/17/2005.	N/A	None
DENSE-017A	Stackable Flex Circuit IC Package and Method of Making Same	Patent	Original	5/5/1999	09/305,384	11/27/2001	6,323,060 B1	Stackable Flex Circuit IC Package and Method of Making Same	Issued. 3 1/2 year maintenance fee due 03/27/2005.	N/A	None
DENSE-017EP	Stackable Flex Circuit IC Package and Method of Making Same	Patent	European	10/26/2001	932131.6			Stackable Flex Circuit IC Package and Method of Making the Same	Closed.	FTO	None
DENSE-017HK	Stackable Flex Circuit IC Package and Method of Making Same	Patent	Hong Kong	9/25/2002	1045759			Stackable Flex Circuit IC Package and Method of Making Same	Closed.	FTO	None
DENSE-017JP	Stackable Flex Circuit IC Package and Method of Making Same	Patent	Japan	10/29/2001	2000-616064			Stackable Flex Circuit IC Package and Method of Making the Same	Closed.	DPAC	5/5/2007
DENSE-017KS	Stackable Flex Circuit IC Package and Method of Making Same	Patent	Korea	11/3/2001	2001-7014056			Stackable Flex Circuit IC Package and Method of Making the Same	Closed.	DPAC	5/5/2005
DENSE-017PC	Stackable Flex Circuit IC Package and Method of Making Same	Patent	PCT	5/5/2000	PCT/US00/12293			Stackable Flex Circuit IC Package and Method of Making Same	Closed.	N/A	None
DENSE-017B	Stackable Flex Circuit Chip Package and Method of Making Same	Patent	Continuation-in-Part	5/19/2000	09/574,321	2/26/2002	6,351,029 B1	Flex Wrap Carrier and Method	Issued. 3 1/2 year maintenance fees due 08/26/2005.	N/A	None
DENSE-017BPC	Stackable Flex Circuit Chip Package and Method of Making Same	Patent	PCT	3/29/2001	PCT/US01/10064			Stackable Flex Circuit Chip Package and Method of Making Same	Closed.	N/A	None

EXHIBIT 1 - DPAC Assets

06/08/04

Updated: January 28, 2004

Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent Trademark Registration Number	Description	Status	Action Required	Date Required Action
DENSE-017BT	Stackable Flex Circuit Chip Package and Method of Making Same	Patent	Taiwan	4/24/2001	90109731			Stackable Flex Circuit Package and Method of Making Same	Closed.	Owner PTO	None
DENSE-017B1	Flex Wrap Carrier and Method	Patent	Continuation-in-Part					Flex Wrap Carrier and Method	Closed, pursuant to client instructions.	N/A	None
DENSE-017BQ	Stackable Flex Circuit Package and Method of Making Same	Patent	Divisional	6/25/2001	09/888,785	7/30/2002	6426240 B1	Stackable Flex Circuit Package and Method of Making Same	Issued, 3 1/2 year maintenance fees due 01/30/2006.	N/A	None
DENSE-017C	Stackable Flex Circuit Chip Package and Method of Making Same	Patent	Continuation	6/25/2001	09/888,792	2/4/2003	6,514,793	Stackable Flex Circuit Chip Package and Method of Making Same	Issued, 3 1/2 year maintenance fees due 08/04/2006.	N/A	None
DENSE-017G	Stackable Flex Circuit and Method of Making Same	Patent	Divisional	11/3/2000	09/706,015	7/30/2002	6,426,349 B1	Stackable Flex Circuit and Method of Making Same	Issued, 3 1/2 year maintenance fees due 01/30/2006.	N/A	None
DENSE-018A	Chip Stack and Method of Making Same	Patent	Original	5/5/1998	09/073,254	1/30/2001	6,180,881 B1	Chip Stack and Method of Making Same	Issued, 3 1/2 year maintenance fees due 07/30/2004.	N/A	None
DENSE-018EP	Chip Stack and Method of Making Same	Patent	European	11/14/2000	99920334.2			Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-018JP	Chip Stack and Method of Making Same	Patent	Japan	10/31/2000	2000-547656			Chip Stack and Method of Making Same	** Closed.	FTO	None
SE-018KS	Chip Stack and Method of Making Same	Patent	Korea	11/6/2000	2000-7012384			Chip Stack and Method of Making Same	Closed.	DPAC	5/4/2004
DENSE-018PC	Chip Stack and Method of Making Same	Patent	PCT		PCT/US99/0744			Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-019A	Module and Method of Making Same	Patent	Original					Module and Method of Making Same	Unfiled - Closed.	N/A	None
DENSE-020A	Chip Stack Having Interconnected Bonding Pads on Staggered Edges of Chips	Patent	Original		08/083,092			Chip Stack Having Interconnected Bonding Pads on Staggered Edges of Chips	Closed.	N/A	None

EXHIBIT 1 - DPAC Assets

Updated: January 28, 2004

Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required Owner	Date Required Action Assigned
DENSE-021A	IC Chip Stack and Method of Making	Patent	Original		08/119,518			IC Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-022A	Memory Module Having Memory Package	Patent	Original		08/083,068			Memory Module Having Memory Package Stages	Closed.	N/A	None
DENSE-023A	Chip Stack and Method of Making Same	Patent	Original		08/093,276			Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-023G	Chip Stack and Method of Making Same	Patent	Divisional		08/097,440			Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-023A	Externally Configurable Chip Carrier	Patent	Original		07/532,578			Externally Configurable Chip Carrier	Closed.	N/A	None
DENSE-026A	Chip Stack with Active Cooling System	Patent	Original	7/13/2000	09/594,363	5/22/2001	6,236,565 B1	Active Cooling System for Chip Stack	Issued. 3 1/2 year maintenance fees due 11/22/2004.	DPAC	None
DENSE-027A	Chip Stack with Differing Chip Package Types	Patent	Original	7/24/2001	09/912,010	9/30/2003	6,627,984	Frame/Multi-Chip Stacking of Differing Package Types	Issued. 3 1/2 year maintenance fee due 03/30/2007.	DPAC	8/3/2003
DENSE-027G	Chip Stack with Differing Chip Package Types	Patent	Divisional	10/3/2002	10/263,859			Frame/Multi-Chip Stacking of Differing Package Types	** Closed.	PTO	None
SE-027PC	Chip Stack with Differing Chip Package Types	Patent	PCT	7/9/2002	PCT/US07/21546			Frame/Multi-Chip Stacking of Differing Package Types	** Closed.	DPAC	1/24/2004
DENSE-028A	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Original	6/21/2000	09/598,373	6/11/2002	6,404,043	Panel Stacking of BGA Devices	Issued. 3 1/2 year maintenance fee due 12/11/2005.	N/A	None
DENSE-028B	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Continuation-in-Part					Panel Stacking of BGA Devices	Closed.	N/A	None
DENSE-028B1	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Continuation-in-Part	12/14/2001	10/017,553	5/20/2003	6,566,746	Panel Stacking of BGA Devices	Issued. 3 1/2 year maintenance fees due 11/20/2006.	N/A	None

EXHIBIT 1 - DPAC Assets

Updated: January 28, 2004

Care	Trademark - Invention	Item Type	Patent Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required	Date Required Action
DENSE028B1G	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Divisional	12/11/2002	10/316,566			Panel Stacking of BGA Devices	** Closed.	PTO	None
DENSE028G	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Divisional	8/6/2001	09/922,977	4/8/2003	6,544,815	Panel Stacking of BGA Devices to Form 3-D Modules	Issued. 3 1/2 year maintenance fees due 10/08/2006.	N/A	None
DENSE028GC	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Continuation	11/8/2002	10/290,994			Panel Stacking of BGA Devices to Form 3-D Modules	** Closed.	PTO	None
DENSE028PC	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	PCT	3/29/2001	PCT/US01/10130			Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Closed.	N/A	None
DENSE028T1	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Taiwan	5/4/2001	90110694			Panel Stacking of BGA Devices to Form Three-Dimensional Modules	** Closed.	DPAC	2/28/2004
DENSE029A	Flux/Underfill Incorporating Ball Spacers	Patent	Original	6/23/2000	09/602,056			Flux/Underfill Incorporating Ball Spacers	Closed.	N/A	None
DENSE030A	Module with One Side Stacked Memory	Patent	Original	1/9/2001	09/757,155			Single Density Board with One Side Stack	Closed	N/A	None
DENSE032A	BGA Device with Flex Flap	Patent	Original					BGA Device with Flex Flap	Closed.	DPAC	None
DENSE033A	Heterogeneous Enhanced L-P Stack	Patent	Original					Heterogeneous Enhanced LP Stack	** Closed.	DPAC	ASAP
DENSE034A	Internal Detectors for Capacitive Coupling Test	Patent	Original	4/19/2002	10/126,760			Internal Detectors for Capacitive Coupling Test	Closed.	PTO	None
DENSE035A	Socketed Stacking	Patent	Original					Socketed Stacking	** Closed	N/A	None
DENSE037A	3-D Memory Stacking Using Anisotropic Epoxy Interconnection	Patent	Original	4/5/2001	09/826,621	10/29/2002	6,472,735	3-D Memory Stacking Using Anisotropic Epoxy Interconnects	Issued. 3 1/2 year maintenance fees due 04/29/2006.	N/A	None

06/08/01

EXHIBIT 1 - DPAC Assets

Updated: January 28, 2004

Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required	Date Required Action
DENSE-037G	Three Dimensional Memory Stacking Using Anisotropic Epoxy Interconnections	Patent	Divisional	3/6/2002	10/092,073			3-D Memory Stacking Using Anisotropic Epoxy Interconnections	Closed.	Owner DPAC	9/18/2003
DENSE-043A	Buried Device Stack	Patent	Original					Buried Device Stack	** Closed.	DPAC	ASAP
DENSE-044A	Slice Interconnect Structure	Patent	Original	6/3/2002	10/161,329			Slice Interconnect Structure	Pending: Awaiting Receipt of Response to Restriction Requirement	PTO	none
DENSE-044N	Slice Interconnect Structure	Patent	Provisional	6/13/2001	60/298,432			Slice Interconnect Structure	Utility Application Filed - See DENSE-044N	N/A	None
DENSE-045A	I/O Interface Structure	Patent	Original	1/4/1900	10/160,857			I/O Interface Structure	** Closed.	PTO	None
DENSE-045N	I/O Interface Structure	Patent	Provisional	6/13/2001	60/298,371			I/O Interface Structure	Utility Application Filed - See DENSE-045N	N/A	None
DENSE-046A	Retaining Ring Interconnect Used for 3-D Stacking	Patent	Original	9/20/2001	09/957,373	6/3/2003	6,573,461	Retaining Ring Interconnect Using 3-D Stacking	Issued. 3 1/2 year maintenance fees due 12/03/2006	N/A	None
DENSE-046G	Retaining Ring Interconnect Used for 3-D Stacking	Patent	Divisional	4/8/2002	10/117,836			Retaining Ring Interconnect Using 3-D Stacking	** Closed.	PTO	None
DENSE-047A	Post in a Ring Interconnect Used for 3-D Stacking	Patent	Original	9/20/2001	09/957,190	6/07/2003	6,573,460	Post in Ring Interconnect Using 3-D Stacking	Issued. 3 1/2 year maintenance fees due 12/03/2006	N/A	None
DENSE-047C	Post in a Ring Interconnect Used for 3-D Stacking	Patent	Divisional	4/5/2002	10/117,245			Post in Ring Interconnect Using 3-D Stacking	** Closed.	PTO	None
DENSE-049A	Thermal Ring Used in 3-D Stacking	Patent	Original	11/6/2001	09/994,002			3-D Stacking Using Thermal Ring	** Closed.	PTO	None
DENSE-051A	A Flex Tab for Use in Stacking Packaged Integrated Circuit Chips	Patent	Original	12/17/2001	10/024,389			Flex Tab Stacking	** Closed.	PTO	None

EXHIBIT 1 - DPAC Assets

Updated: January 28, 2004

Case	Title/Mark - Invention	Item Type	Patent Trade-mark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required by Owner	Date Requested Action Assigned
DENSE-052A	CSP Chip Stack with Flex Circuit	Patent	Original	12/14/2001	10/016,939			C-S Stack with Double Sided Flex and Formed Lead	** Closed.	PTO	None
DENSE-053A	Folded Flex Circuit with z-axis Interconnect	Patent	Original					Folded Flex Circuit with z-axis Interconnect	Closed.	DPAC	None
DENSE-055A	CS-STACK	Patent	Original					CS-STACK	Closed.	N/A	None
DENSE-059A	Trench Transposer	Patent	Original	4/7/2003	10/408,317			Trench Transposer	** Closed.	PTO	None
DENSE-060A	Integrated Z-Axis Interconnect on Post Processed Chip Scale Package	Patent	Original					Integrated Z-Axis Interconnect on Post Processed Chip Scale Package	Closed.	DPAC	None
DENSE-061A	Direct Die Scale	Patent	Original					Direct Die Scale	Closed.	DPAC	None
DENSE-062A	Near Die Stack	Patent	Original					Near Die Stack	Closed.	DPAC	None
DENSE-065A	T.S.O.P STACKING USING LASER/SPOT WELDING INTERCONNECT	Patent	Original					T.S.O.P STACKING USING LASER/SPOT WELDING INTERCONNECT	Closed (Combined with DENSE-067A)	N/A	None
DENSE-066A	TSOP STACKING USING UNDERLEAD INTERPOSER	Patent	Original	4/7/2009	10/408,697			TSOP STACKING USING UNDERLEAD INTERPOSER	** Closed.	PTO	None
DENSE-067A	THIN SCALE OUTLINE PACKAGE STACK	Patent	Original	12/5/2002	10/310,368			THIN SCALE OUTLINE PACKAGE STACK	Response to OA due 6/24/04	PTO	6/24/04
DENSE-067B	THIN SCALE OUTLINE PACKAGE STACK	Patent	Combination-Id-Part	7/14/03	10/620,157			THIN SCALE OUTLINE PACKAGE STACK	Awaiting Receipt of Response to Restriction Requirement	DPAC	None
DENSE-067S	T.S.O.P STACK PATENT SEARCH	Patent	Search					T.S.O.P STACK PATENT SEARCH	Patent Search Opinion Letter to client 12/31/2002.	N/A	None

06/08/04

EXHIBIT 1 - DPAC Assets

Updated: January 28, 2004

Cue	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required	Date Required Action Assigned
DENSE-068A	T.S.O.P. POLYIMIDE FILM STRIP STACK	Patent	Original					T.S.O.P. POLYIMIDE FILM STRIP STACK	** Closed.	DPAC	None
DENSE-069A	TRANSPOSER CONVERTER FOR MONOLITHIC TO STACKABLE	Patent	Original					TRANSPOSER CONVERTER FOR MONOLITHIC TO STACKABLE	** Closed.	DPAC	None
DENSE-070A	STAR-STEP SIGNAL ROUTING	Patent	Original	4/21/2003	10/420,485			STAR-STEP SIGNAL ROUTING	Awaiting Receipt of Final Office Action	PTO	None
DENSE-071N	METHOD TO ACCESS SCALABLE ARRAYS OF MEMORY VIA HYPER TRANSPORT BUSES	Patent	Provisional					METHOD TO ACCESS SCALABLE ARRAYS OF MEMORY VIA HYPER TRANSPORT BUSES	Closed.	N/A	None
DENSE-072A	TSOP STACK ENHANCEMENTS	Patent	Original					TSOP STACK ENHANCEMENTS	Closed.	DPAC	None

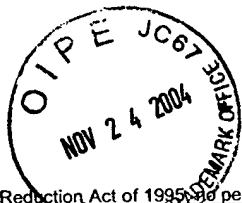
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DPAC
STAKTEK

PTO/SB/17 (10-03)

Approved for use through 07/31/2006. OMB 0651-0032
U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

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FEE TRANSMITTAL

for FY 2004

Effective 10/01/2003. Patent fees are subject to annual revision.

☐ Applicant claims small entity status. See 37 CFR 1.27

TOTAL AMOUNT OF PAYMENT (\$) 40.00

Complete if Known

Application Number	09/633,297
Filing Date	08/03/2000
First Named Inventor	A. Levy, et al
Examiner Name	D. Graybill
Art Unit	2827
Attorney Docket No.	DPAC-015X

METHOD OF PAYMENT (check all that apply)☐ Check ☐ Credit card ☐ Money Order ☐ Other ☐ None☒ Deposit Account:Deposit Account Number
Deposit Account Name

50-0897

Andrews Kurth LLP

The Director is authorized to: (check all that apply)

☒ Charge fee(s) indicated below ☒ Credit any overpayments☒ Charge any additional fee(s) or any underpayment of fee(s)☐ Charge fee(s) indicated below, except for the filing fee to the above-identified deposit account.**FEE CALCULATION****1. BASIC FILING FEE**

Large Entity Fee Code (\$)	Small Entity Fee Code (\$)	Fee Description	Fee Paid
1001 770	2001 385	Utility filing fee	
1002 340	2002 170	Design filing fee	
1003 530	2003 265	Plant filing fee	
1004 770	2004 385	Reissue filing fee	
1005 160	2005 80	Provisional filing fee	

SUBTOTAL (1) (\$)

2. EXTRA CLAIM FEES FOR UTILITY AND REISSUE

	Extra Claims	Fee from below	Fee Paid
Total Claims	-20** =	X	
Independent Claims	-3** =	X	
Multiple Dependent			

Large Entity Fee Code (\$)	Small Entity Fee Code (\$)	Fee Description
1202 18	2202 9	Claims in excess of 20
1201 86	2201 43	Independent claims in excess of 3
1203 290	2203 145	Multiple dependent claim, if not paid
1204 86	2204 43	** Reissue independent claims over original patent
1205 18	2205 9	** Reissue claims in excess of 20 and over original patent

SUBTOTAL (2) (\$)

**or number previously paid, if greater; For Reissues, see above

FEE CALCULATION (continued)**3. ADDITIONAL FEES**

Large Entity Small Entity

Fee Code (\$)	Fee Code (\$)	Fee Description	Fee Paid
1051 130	2051 65	Surcharge - late filing fee or oath	
1052 50	2052 25	Surcharge - late provisional filing fee or cover sheet	
1053 130	1053 130	Non-English specification	
1812 2,520	1812 2,520	For filing a request for <i>ex parte</i> reexamination	
1804 920*	1804 920*	Requesting publication of SIR prior to Examiner action	
1805 1,840*	1805 1,840*	Requesting publication of SIR after Examiner action	
1251 110	2251 55	Extension for reply within first month	
1252 420	2252 210	Extension for reply within second month	
1253 950	2253 475	Extension for reply within third month	
1254 1,480	2254 740	Extension for reply within fourth month	
1255 2,010	2255 1,005	Extension for reply within fifth month	
1401 330	2401 165	Notice of Appeal	
1402 330	2402 165	Filing a brief in support of an appeal	
1403 290	2403 145	Request for oral hearing	
1451 1,510	1451 1,510	Petition to institute a public use proceeding	
1452 110	2452 55	Petition to revive - unavoidable	
1453 1,330	2453 665	Petition to revive - unintentional	
1501 1,330	2501 665	Utility issue fee (or reissue)	
1502 480	2502 240	Design issue fee	
1503 640	2503 320	Plant issue fee	
1460 130	1460 130	Petitions to the Commissioner	
1807 50	1807 50	Processing fee under 37 CFR 1.17(q)	
1806 180	1806 180	Submission of Information Disclosure Stmt	
8021 40	8021 40	Recording each patent assignment per property (times number of properties)	40.00
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1810 770	2810 385	For each additional invention to be examined (37 CFR 1.129(b))	
1801 770	2801 385	Request for Continued Examination (RCE)	
1802 900	1802 900	Request for expedited examination of a design application	

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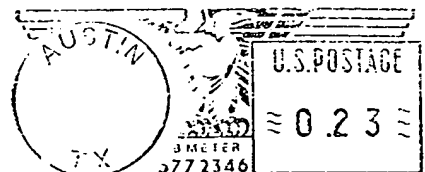
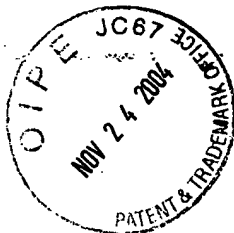
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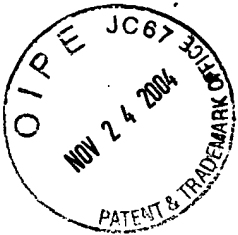
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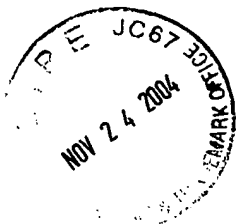
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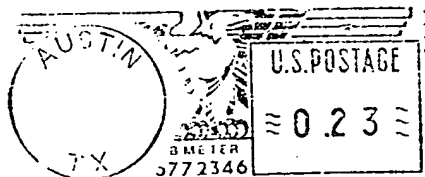
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